# MA2C188 (MA188)

### Silicon epitaxial planar type

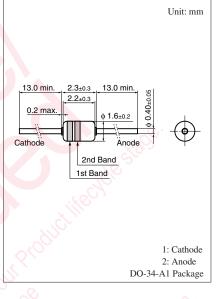
For high speed and high voltage switching, small-power rectification

#### Features

- Allowing to insert into a 5 mm pitch hole
- High voltage (V<sub>R</sub>: 200 V) rectification is possible

Absolute Maximum natings $T_a = 25$ C						
Parameter	Symbol	Rating	Unit			
Reverse voltage	V <sub>R</sub>	200	V			
Maximum peak reverse voltage	V <sub>RM</sub>	250	V			
Power dissipation (Average)	P <sub>D(AV)</sub>	400	mW			
Output current	I <sub>0</sub>	200	mA			
Repetitive peak forward current	I <sub>FRM</sub>	625	mA			
Non-repetitive peak forward surge current *	I <sub>FSM</sub>	1	A			
Junction temperature	Tj	175	°C			
Storage temperature	T <sub>stg</sub>	-65 to +175	°¢			



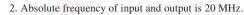


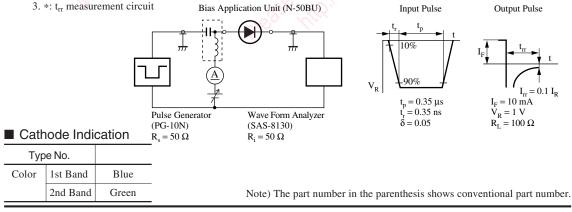
Note) \*: t = 1 s

#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V <sub>F</sub>	$I_{\rm F} = 200  {\rm mA}$	00	SOL	1.2	V
Reverse voltage	V <sub>R</sub>	$I_R = 100 \ \mu A$	250	0.0		V
Reverse current	S I <sub>R</sub>	$V_{R} = 200 V$	2°°		200	nA
Terminal capacitance	C <sub>t</sub>	$V_R = 0 V, f = 1 MHz$		1.0		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = 10 \text{ mA}, V_R = 1 \text{ V}$			60	ns
		$I_{rr} = 0.1 I_R, R_L = 100 \Omega$				

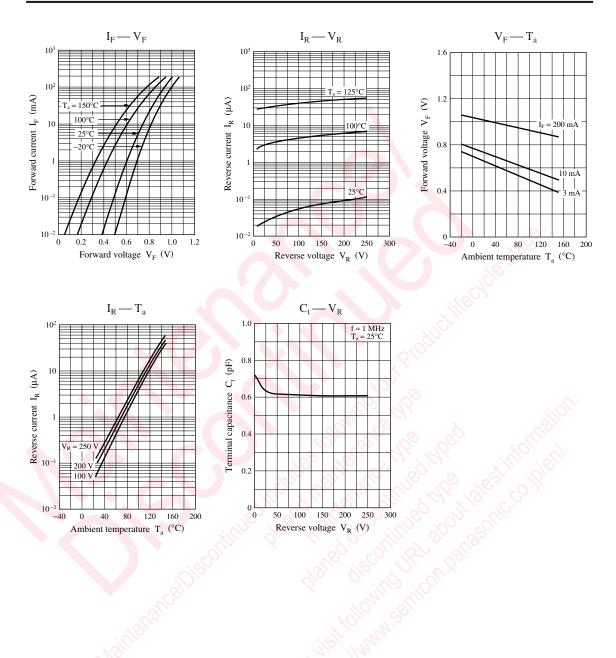
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.





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